

Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	-40	V		
Gate-Source Voltage	V _{GSS}	±25	V		
Continuous Prain Correct (Nata C) // 40 //	Steady State	$T_C = +25$ °C $T_C = +70$ °C	l _D	-50 -40	А
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-15 -12	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	-100	Α		
Maximum Body Diode Forward Current (Note 6)	Is	-5.5	Α		
Avalanche Current, L = 1mH (Note 7)	I _{AS}	-22	Α		
Avalanche Energy, L = 1mH (Note 7)	E _{AS}	260	mJ		

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	1.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	73	°C/W
Total Power Dissipation (Note 6)		P_{D}	3.3	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State R _{0JA} 38		°C/W	
Thermal Resistance, Junction to Case	R _{θJC}	1.0	C/VV	
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

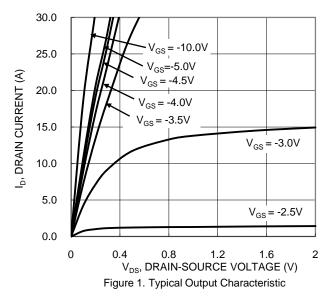
Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-1.5	-2	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance		_	7.5	9.9	mΩ	$V_{GS} = -10V, I_D = -9.8A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	10.5	14	11177	$V_{GS} = -4.5V, I_D = -9.8A$	
Diode Forward Voltage	V _{SD}	_	-0.7	-1	V	V _{GS} = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	4,234	_		V _{DS} = -20V, V _{GS} = 0V f = 1MHz	
Output Capacitance	Coss	_	1,036	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	526	_			
Gate Resistance	R_g	_	7.8	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	42.7			V _{DS} = -20V, I _D = -9.8A	
Total Gate Charge (V _{GS} = -10V)	Qg	_	91	_	nC		
Gate-Source Charge	Qgs	_	14.2		nc nc		
Gate-Drain Charge	Q_{qd}	_	13.5	_			
Turn-On Delay Time	t _{D(ON)}	_	13.2			$V_{GS} = -10V, V_{DD} = -20V,$ $R_{G} = 6\Omega, I_{D} = -1A$	
Turn-On Rise Time	t _R	_	10	_			
Turn-Off Delay Time	t _{D(OFF)}	_	303		ns		
Turn-Off Fall Time	t _F	_	138	_			
Reverse Recovery Time	t _{RR}		26	_	ns	I _F = -9.8A, di/dt = -100A/µs	
Reverse Recovery Charge	Q _{RR}	_	20	_	nC	I _F = -9.8A, di/dt = -100A/µs	

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

- 7. IAS and EAS ratings are based on low frequency and duty cycles to keep $T_J = +25$ °C.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.





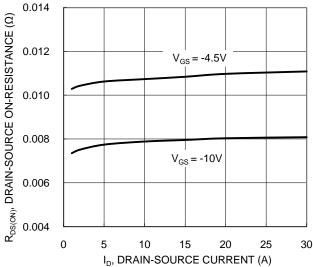


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

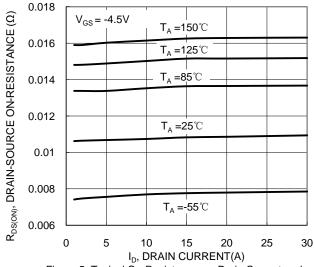
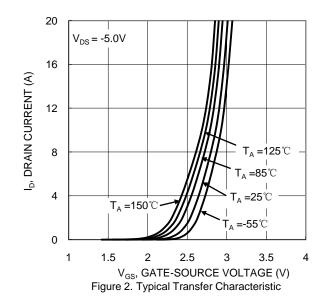
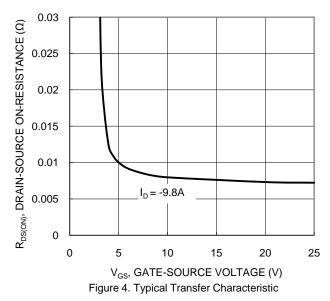


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





1.8 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) $V_{GS} = -10V, I_{D} = -9.8A$ 1.6 1.4 1.2 1 0.8 $V_{GS} = -4.5V, I_{D} = -9.8A$ 0.6 -25 0 25 50 75 100 125 150 -50 T_J , JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Temperature



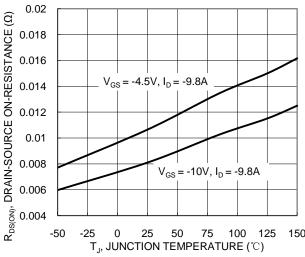
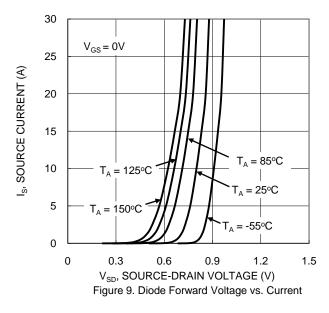
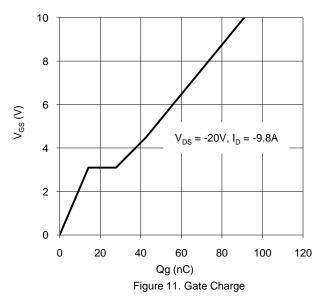


Figure 7. On-Resistance Variation with Temperature





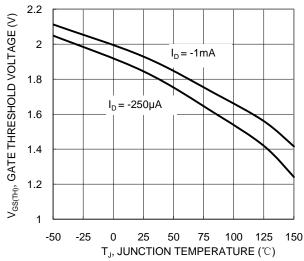
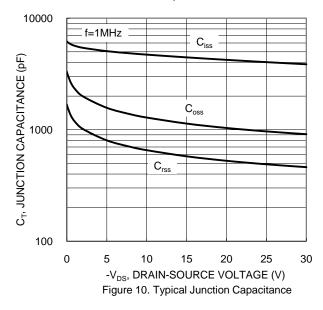
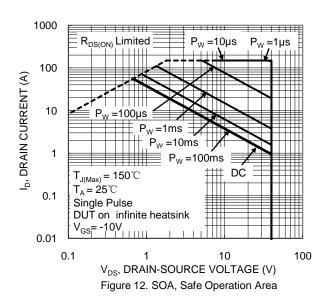


Figure 8. Gate Threshold Variation vs. Junction Temperature







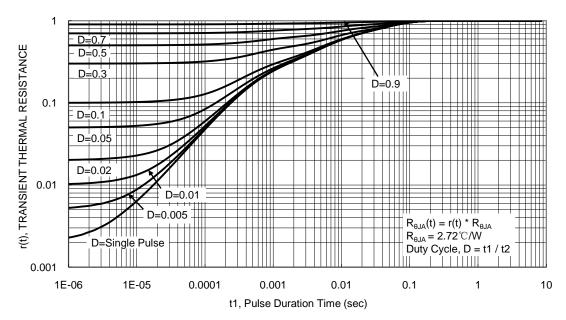
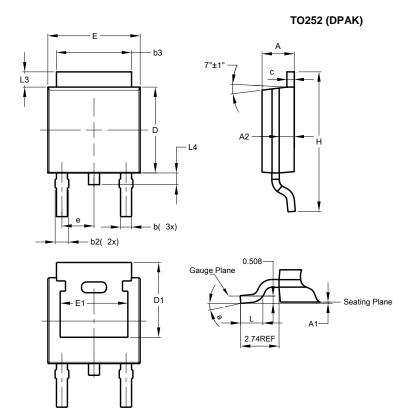


Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

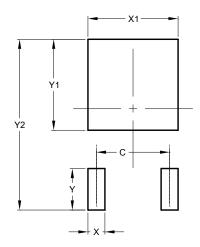


TO252 (DPAK)						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A 1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
b	0.64	0.88	0.783			
b2	0.76	1.14	0.95			
b3	5.21	5.46	5.33			
С	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	_	_			
е	_	_	2.286			
П	6.45	6.70	6.58			
E1	4.32	_	_			
H	9.40	10.41	9.91			
Г	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
L4	0.64	1.02	0.83			
а	0°	10°	_			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Υ	2.600		
Y1	5.700		
Y2	10 700		



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